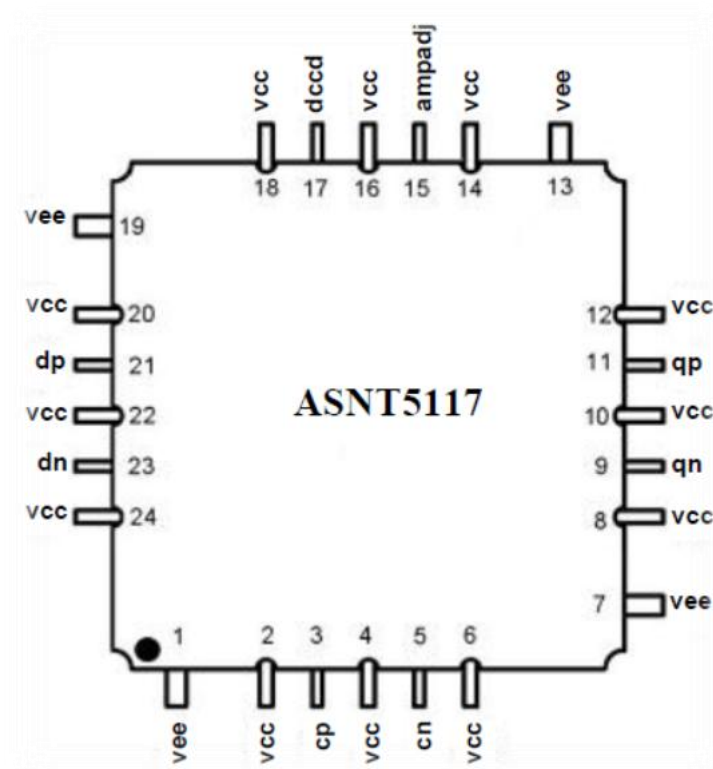




ASNT5117-KMC DC-40 Gbps D-Type Flip-Flop with Amplitude Adjust

- High speed broadband D-Type Flip-Flop for data retiming with full rate clock
- Input data common mode control
- Exhibits low jitter and limited temperature variation over industrial temperature range
- 4ps set-up/hold time capability
- 88% clock phase margin for retiming of data input eye
- Fully differential CML input interfaces
- Fully differential CML output interface with adjustable 0 to 900mV single-ended swing
- Single +3.3V or -3.3V power supply
- Power consumption: 726mW
- Fabricated in SiGe for high performance, yield, and reliability
- Custom CQFP 24-pin package



DESCRIPTION

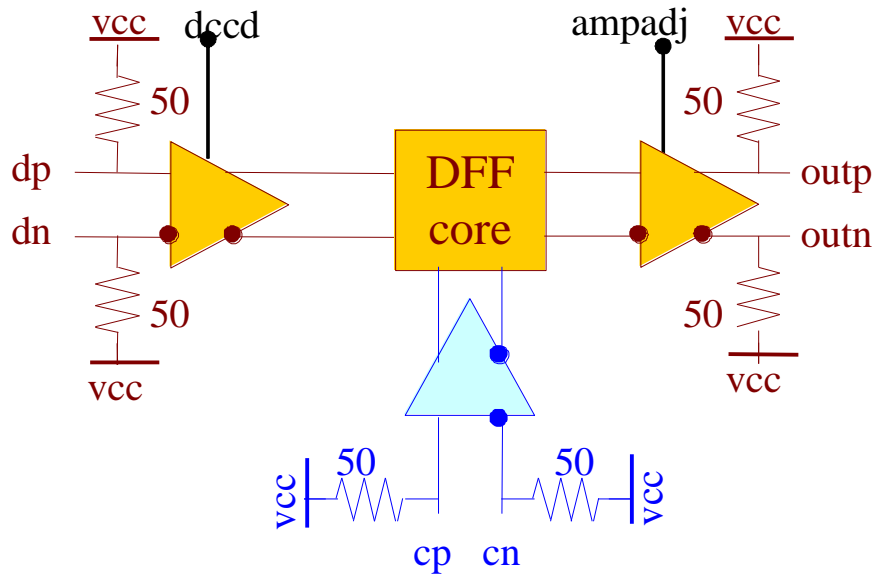


Fig. 1. Functional Block Diagram

The temperature stable ASNT5117-KMC SiGe IC provides broadband data retiming functionality and is intended for use in high-speed measurement / test equipment. The IC shown in Fig. 1 can sample a high-speed data signal dp/dn with a full-rate external clock cp/cn to create a full-rate retimed NRZ data output qp/qn . The internal DC common mode voltage levels on data inputs dp/dn can be adjusted by applying analog voltage to the control input $dccd$. The output amplitude of the DFF is adjustable by using the control voltage $ampadj$.

The part's I/O's support the CML logic interface with on chip equivalent 50Ω termination and may be used differentially, AC/DC coupled, single-ended, or in any combination (see also POWER SUPPLY CONFIGURATION).

HS Clock Input Buffer

The buffer can accept high-speed signals at its differential CML input port cp/cn . It can also accept a single-ended signal with a threshold voltage applied to the unused pin. It can handle a wide range of input signal amplitudes. The buffer utilizes on-chip single-ended 50Ω termination to vcc for each input line.

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The buffer allows for adjustment of its input DC common-mode voltage by changing the control voltage $dccd$ following the diagram shown in Fig. 2. Here the x-axis presents the $dccd$ values, the y-axis presents the common-mode voltage values, the red lines correspond to the dp input, the blue lines correspond to



the dn input, and the solid lines represent typical conditions while dotted and dashed lines represent slow and fast conditions respectively.

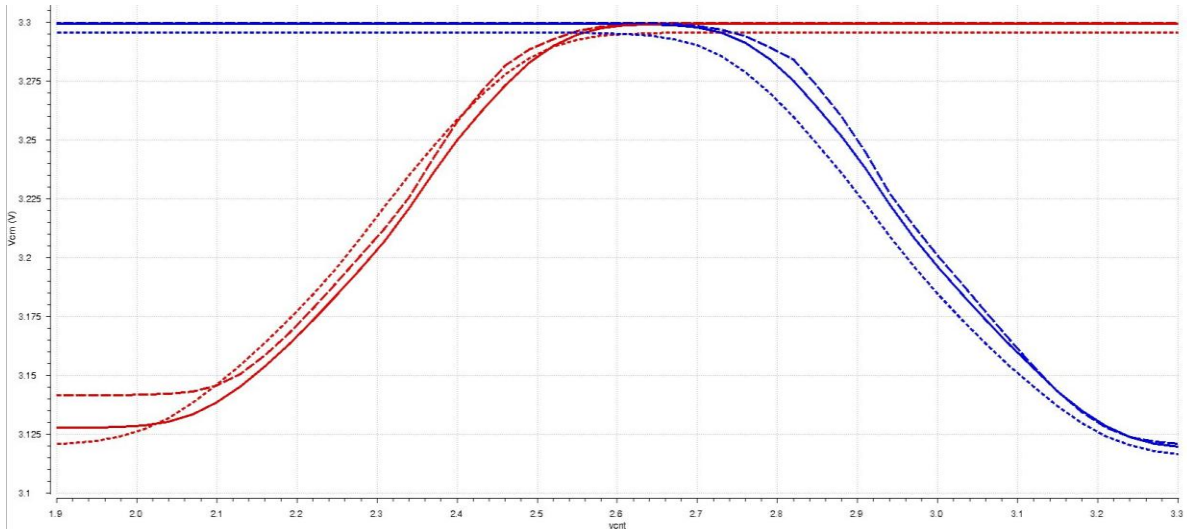


Fig. 2. Duty Cycle Control Diagram

HS Data Output Buffer

The buffer receives high-speed serial data from the DFF core and converts it into a differential CML output signal q_p/q_n . Each buffer utilizes internal single-ended 50Ω loads to v_{cc} and requires single-ended 50Ω external termination. The termination resistors can be connected from each output directly to v_{cc} , or through DC blocks to v_{ee} . The amplitude of the output signals can be adjusted from $0V$ to its maximum value using the external control voltage $ampadj$.

POWER SUPPLY CONFIGURATION

The part can operate with either a negative supply ($v_{cc} = 0.0V = \text{ground}$ and $v_{ee} = -3.3V$), or a positive supply ($v_{cc} = +3.3V$ and $v_{ee} = 0.0V = \text{ground}$). In case of a positive supply, all I/Os need AC termination when connected to any devices with 50Ω termination to ground. Different PCB layouts will be needed for each different power supply combination.

All the characteristics detailed below assume $v_{cc} = 0.0V$ and $v_{ee} = -3.3V$.

ABSOLUTE MAXIMUM RATINGS

Caution: Exceeding the absolute maximum ratings shown in *Table 1* may cause damage to this product and/or lead to reduced reliability. Functional performance is specified over the recommended operating conditions for power supply and temperature only. AC and DC device characteristics at or beyond the absolute maximum ratings are not assumed or implied. All min and max voltage limits are referenced to ground (assumed v_{cc}).



Parameter	Min	Max	Units
Supply Voltage (vee)		-3.6	V
Power Consumption		0.80	W
Input Data Voltage Swing (SE)		1.0	V
Input Clk Voltage Swing (SE)		1.0	V
Case Temperature		+90	°C
Storage Temperature	-40	+100	°C
Operational Humidity	10	98	%
Storage Humidity	10	98	%

Table 1. Absolute Maximum Ratings

TERMINAL FUNCTIONS

TERMINAL			Pin function	Default state	Termination
Name	No.	Type			
High-Speed I/Os					
dp	21	CML	Input data		SE 50Ohm to vcc
dn	23	Input			
cp	3	CML	Input clock		SE 50Ohm to vcc
cn	5	Input			
qp	11	CML	Output data.		SE 50Ohm to vcc. Require external SE 50Ohm to vcc
qn	9	Output			
DC Controls					
ampadj	15	Analog voltage	Output data amplitude control		2.3KOhm to vcc, 9.3KOhm to vee
dccd	17		Input data common mode voltage control		5.6KOhm to vcc, 22.2KOhm to vee
Supply and Termination Voltages					
Name	Description		Pin Number		
vcc	Positive power supply (+3.3V or 0V)		2, 4, 6, 8, 10, 12, 14, 16, 18, 20, 22, 24		
vee	Negative power supply (0V or -3.3V)		1, 7, 13, 19		



ELECTRICAL CHARACTERISTICS

PARAMETER	MIN	TYP	MAX	UNIT	COMMENTS
General Parameters					
vcc		0.0		V	External ground
vee	-3.1	-3.3	-3.5	V	±6%
Ivcc		220	233	mA	
Power consumption		726	770	mW	
Junction temperature	-25	50	125	°C	
HS Input Data (dp/dn)					
Data rate	DC	32	40	Gbps	
Swing	0.05		0.8	V	Differential or SE, p-p
CM Voltage Level	vcc-0.7+sw/2	vcc+0.6-sw/2		V	Must match for both inputs
HS Input Clock (cp/cn)					
Frequency	DC	32	40	GHz	
Swing	0.05		0.8	V	Differential or SE, p-p
CM Voltage Level	vcc-0.7	vcc+0.6-sw/2		V	Must match for both inputs
Duty Cycle	40	50	60	%	
Clock phase margin	86	88	90	%	For reliable data latching
HS Output Data (qp/qn)					
Data rate	DC	32	40	Gbps	
Logic "1" level	vcc-0.05	vcc-0.03	vcc-0.01	V	
Logic "0" level	Equal to logic "1"			V	With ampadj set at minimum
	vcc-0.42	vcc-0.40	vcc-0.38	V	With ampadj set at default
	vcc-0.90	vcc-0.80	vcc-0.78	V	With ampadj set at maximum
Jitter		1.5		ps	Peak-to-peak at 32Gbps
DC Input Controls (dccd, ampadj)					
Max level		vcc		V	
Min level		vcc - 1.3		V	

PACKAGE INFORMATION

The chip die is housed in a custom 24-pin CQFP package shown in Fig. 3. The package provides a center heat slug located on its back side to be used for heat dissipation. ADSANTEC recommends for this section to be soldered to the vcc plain, which is ground for a negative supply, or power for a positive supply.

The part's identification label is ASNT5117-KMC. The first 8 characters of the name before the dash identify the bare die including general circuit family, fabrication technology, specific circuit type, and part version while the 3 characters after the dash represent the package's manufacturer, type, and pin out count.

This device complies with the Restriction of Hazardous Substances (RoHS) per EU 2002/95/EC for all six substances.



REVISION HISTORY

Revision	Date	Changes
1.2.2	07-2019	Updated Letterhead
1.2.1	10-2015	Corrected electrical characteristics section Updated package information section
1.1.1	04-2015	Updated maximum frequency of operation Updated maximum output amplitude
1.0.1	04-2015	First release